

SuperStorage 6019P-ACR12L+



Integrated Board



Super X11DDW-NT

Views: | [Angled View](#) | [Top View](#) |
| [Front View](#) | [Rear View](#) |

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Key Features

- High Density Storage
- Object Storage 1U
- Scale-out Storage
- Ceph / Hadoop
- Big Data Analytics

1. Dual Socket P (LGA 3647) support 2nd Gen. Intel® Xeon® Scalable processors (Cascade Lake/Skylake)[‡]
2. 12 DIMMs; up to 3TB 3DS ECC DDR4-2933MHz[†] RDIMM/LRDIMM, Supports Intel® Optane™ DCPMM^{††}
3. 3 PCI-E 3.0 x16 slots, 1 PCI-E 3.0 x4 NVMe M.2 slot
4. 12 Hot-swap 3.5" SAS3/SATA3, 4 Hot-swap 2.5" 7mm NVMe/SATA drive bays
5. 2x 10GBase-T ports via Intel C622
6. IPMI 2.0 + KVM with Dedicated LAN
7. 1 VGA, 4 USB 3.0 (rear)
8. Internal Cable Arm
9. 800W Redundant Power Supplies **Platinum Level Certified**

Note: Image above may show a varied configuration of optional parts. Please refer to parts list for standard parts included.

Specifications

Product SKUs

- SSG-6019P-ACR12L+ ■ SuperStorage 6019P-ACR12L+ (Black)

Motherboard

Super X11DDW-NT

Processor/Cache

- CPU**
 - Dual Socket P (LGA 3647)
 - 2nd Gen Intel® Xeon® Scalable Processors and Intel® Xeon® Scalable Processors[‡], Dual UPI up to 10.4GT/s
 - Support CPU TDP up to 205W^{†††}

- Cores** ■ Up to 28 Cores

- Note**
 - ‡ BIOS version 3.2 or above is required to support 2nd Gen Intel® Xeon® Scalable processors (codenamed Cascade Lake-R)
 - ††† 205W CPU support for high performance up to 32°C. 75W-165W CPU support from 10°C ~ 35°C.

System Memory

- Memory Capacity**
 - 12 DIMM slots
 - Up to 3TB 3DS ECC DDR4-2933MHz[†] RDIMM/LRDIMM
 - Supports Intel® Optane™ DCPMM^{††}

- Memory Type** ■ 2933[†]/2666/2400/2133MHz ECC DDR4 RDIMM/LRDIMM

- Note**
 - † 2933MHz in two DIMMs per channel can be achieved by using memory purchased from Supermicro
 - †† Cascade Lake only. Contact your Supermicro sales rep for more info.

On-Board Devices

- Chipset** ■ Intel® C622 chipset
- SATA** ■ SATA3 (6Gbps); RAID 0, 1, 5, 10
- Network Controllers** ■ Dual LAN with 10GBase-T from Intel C622
- IPMI**
 - Support for Intelligent Platform Management Interface v.2.0
 - IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
- Video** ■ ASPEED AST2500 BMC

Input / Output

- LAN**
 - 2 RJ45 10GBase-T LAN ports
 - 1 RJ45 Dedicated IPMI LAN port
- USB**
 - 4 USB 3.0 ports (rear)
 - 2 USB 2.0 ports (front)
- Video** ■ 1 VGA port
- TPM** ■ 1 TPM Header

Chassis

- Form Factor** ■ 1U Rackmount

- Model** ■ CSE-802TS-R804WBP

Dimensions and Weight

- Width** ■ 17.6" (447mm)
- Height** ■ 1.7" (43mm)
- Depth** ■ 37.40" (950mm)**
- Weight**
 - Net Weight: 65 lbs (29.5 kg)
 - Gross Weight: 80 lbs (36.3 kg)
- Available Colors** ■ Black

Front Panel

- Buttons**
 - Power On/Off button
 - System Reset button
- LEDs**
 - Power status LED
 - HDD activity LED
 - Network activity LEDs

Expansion Slots

- PCI-Express**
 - 3 PCI-E 3.0 x16 slots
 - 1 PCI-E 3.0 x4 NVMe M.2 slot
 - AOM slot (AOM Broadcom 3216 SAS3 IT Mode)

Drive Bays

- Hot-swap**
 - 12 Hot-swap 3.5" SAS3/SATA3 drive bays
 - 4 Hot-swap 2.5" 7mm NVMe/SATA drive bays

System Cooling

- Fans** ■ 6x 40x40x56mm 20.5K-17.6K RPM Counter-rotating fans

Power Supply

800W Redundant Power Supplies with PMBus

- Total Output Power** ■ 800W
- Dimension (W x H x L)** ■ 54.5 x 40.25 x 220 mm
- Input**
 - 750W: 100-127Vac / 10A
 - 800W: 200-240Vac / 5.5A
 - 800W: 230-240Vdc / 5.5A
- +12V**
 - Max: 62.5A /Min: 0.5A (100-127Vac)
 - Max: 66.6A /Min: 0.5A (200-240Vac, 230-240Vdc)
- +5Vsb** ■ Max: 4A /Min: 0A
- Output Type** ■ Gold Finger

System BIOS

- BIOS Type** ■ UEFI 256Mb
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Management

- Software**
- Intel® Node Manager
 - IPMI 2.0
 - KVM with dedicated LAN
 - SSM, SPM, SUM
 - SuperDoctor® 5
 - Watch Dog
-

- Power Configurations** ■ ACPI / APM Power Management
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PC Health Monitoring

- CPU**
- Monitors for CPU Cores, Chipset Voltages, Memory.
 - 4+1 Phase-switching voltage regulator
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- FAN**
- Fans with tachometer monitoring
 - Status monitor for speed control
 - Pulse Width Modulated (PWM) fan connectors
-

- Temperature**
- Monitoring for CPU and chassis environment
 - Thermal Control for fan connectors
-

Certification



Platinum Level

Operating Environment

- RoHS** ■ RoHS Compliant
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- Environmental Spec.**
- Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F)
 - Non-operating Temperature: -40°C to 60°C (-40°F to 140°F)
 - Operating Relative Humidity: 8% to 90% (non-condensing)
 - Non-operating Relative Humidity: 5% to 95% (non-condensing)
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Parts List

Parts List - (Items Included)

| | Part Number | Qty | Description |
|------------------------------|-------------------|-----|---|
| Motherboard / Chassis | MBD-X11DDW-NT | 1 | Super X11DDW-NT Motherboard |
| | CSE-802TS-R804WBP | 1 | 1U Chassis |
| Add-on Card / Module | AOM-S3216-L-2-P | 1 | SAS 16-port mezzanine controller based on Broadcom 3216 IOC. |
| Backplane | BPN-NVME3-802N-S4 | 1 | 4-Port Hybrid Backplane Supports 4 x 2.5 |
| Backplane | BPN-SAS3-802A-2 | 3 | 4-Port Backplane Supports 4 x 3.5" SAS/SATA HDD,HF,RoHS |
| Cable 1 | CBL-0174L | 2 | PWCD,US,NEMA5-15P TO IEC60320 C13,6FT,14AWG,15A,125V,RoHS/REACH |
| Cable 2 | CBL-CDAT-0930 | 1 | CBL,7PIN TO 7PIN,P1.5/1.0mm,17.2CM,26/28AWG,RoHS |
| Cable 3 | CBL-PWCD-0174-IS | 2 | PWCD,US,NEMA5-15P TO IEC60320 C13,6FT,14AWG,RoHS/REACH |
| Cable 4 | CBL-PWEX-1056 | 1 | BPN PWR,2P/P3.0 to 3P/P3.0, 12V, 60CM,18AWG, 6A/pin, -20~80C, RoHS |
| Cable 5 | CBL-SAST-0830 | 4 | OcuLink v 1.0,INT,PCIe NVMe SSD,Passive Latch, 80 |
| Cable 6 | CBL-SAST-0831 | 1 | OcuLink v 1.0,INT,PCIe NVMe SSD, Passive Latch, to MiniSAS 95CM,32AWG |
| Cable 7 | CBL-SAST-1028 | 1 | SLIMLINE SAS, INT,Passive Latch,91.9CM, power x4, 17/19.8CM |
| Front Panel | FPB-802A-LED12 | 1 | SC802 front HDD LED board,RoHS |
| Parts | MCP-150-00015-0B | 2 | Rubber pad, 3.0mm H, 10x10mm |
| Riser Card | RSC-R1UW-2E16 | 1 | 1U LHS WIO Riser card with two PCI-E x16 slots |
| Riser Card | RSC-WR-6 | 1 | 1U RHS WIO Riser card with one PCI-E 4.0 x16 slot,HF,RoHS |
| Heatsink / Retention | SNK-P0067PS | 2 | 1U Passive CPU Heat Sink for X11 Purley Platform Equipped with a Narrow Retention Mechanism |
| * Power Supply | PWS-804P-1R | 2 | 1U 800W 100-240VAC/50-60Hz, and DC240V input |
| * Power Distributor | PDB-PT802-8824 | 1 | 1U Power Distributor Board for SC802 support up to 800W.,RoH |

Notes:

1. Parts with * are inside the chassis
2. Excessive parts might not be shipped, including but not limited to excessive drive trays, fans, riser brackets, air shrouds, IO shields, cables.....etc.

Optional Parts List

| | Part Number | Qty | Description |
|------------------------|--------------------------------------|-------------------|---|
| Network Card(s) | AOC-SGP-i2 | - | Standard LP, 2x GbE RJ45, PCI-E x4, Intel® i350AM2 |
| | AOC-SGP-i4 | - | Standard LP, 4x GbE RJ45, PCI-E x4, Intel® i350 |
| | AOC-SG-i2 | - | Standard LP, 2x GbE RJ45, PCI-E x4, Intel® 82575EB |
| | AOC-SG-i4 | - | Standard LP, 4x GbE RJ45, PCI-E x4, Intel® 82576EB |
| | AOC-STG-b4S | - | Standard LP, 4x 10GbE SFP+, PCI-E x8, Broadcom® BCM57840S |
| | AOC-STGN-i2S | - | Standard LP, 2x 10GbE SFP+, PCI-E x8, Intel® 82599ES |
| | AOC-STGN-i1S | - | Standard LP, 1x 10GbE SFP+, PCI-E x8, Intel® 82599ES |
| | AOC-STG-i2T | - | Standard LP, 2x 10GbE RJ45, PCI-E x8, Intel® X540 |
| | AOC-STG-i2 | - | Standard LP, 2x 10GbE CX4, PCI-E x8, Intel® 82598EB |
| | Global Services & Support | <u>OS4HR3/2/1</u> | - |
| <u>OSNBD3/2/1</u> | | - | 3/2/1-year onsite NBD service |
| Software | <u>SFT-OOB-LIC</u> • eStore | 1 | OOB Management Package (per node license) |
| Software | <u>SFT-DCMS-Single</u> | 1 | DataCenter Management Package (per node license) |

